NEW

0.35mm Pitch, 2.0mm Depth, 0.6mm Stacking Height Multi-RF Compatible Board-to-Board Connector

**BM46** Series



### Features

- 1. Multi-RF capable Board-to-Board connector, World's smallest width class Pitch : 0.35mm, Width : 2.0mm, Stacking height : 0.6mm
- 2. Contact design ideal for both high speed digital transmission and RF signal
- 3. Superior RF Signal Transmission V.S.W.R. 0-3GHz : 1.3 Max. 3-6GHz : 1.4 Max.

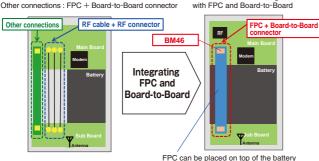
6-12GHz : 1.6 Max.

- 4. Center shield prevents signal noise between opposing rows
- 5. Robust metal mating guides

## Applications

Thin devices such as cell phones, tablet PCs, routers, etc. that require spacesaving components.

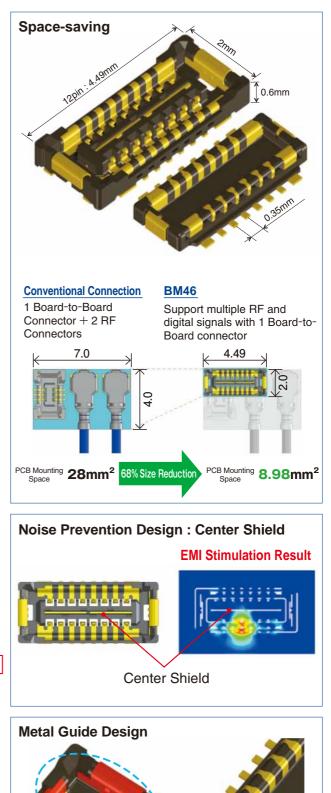
Conventional Internal Connection RF connection : RF cable + RF connector Other connections : FPC + Board-to-Board connector



## Environmental

### Halogen-free\*

In accordance with IEC 61249-2-21 Br : 900ppm max, CI : 900ppm max Br+CI : 1500ppm max



In cases where the application will demand a high level of reliability, such as automotive, please contact a company representative for further information.

New Proposed Design

Connect RF and other signals

2019.11 **HS** 1

### Product Specifications

Product Speci	icalio	115				
Rated Current : Signal Conta	act : 0.3A	Operating Temperature : -55 to +85°C (Note 1)		Storage Temperature Range : -55 to +60°C		
Rated Voltage 30V AC/DC				Operating Humidity Range : 90% RH Max. (Note 2, 3)		
Characteristic Impedance : 5	60Ω	Rated Frequency : DC to 12 GHz	2			
Item		Specifications	Conditions			
1. Contact Resistance	Signal C	ontact 100mΩ Max.	Measured	d at 20mV AC, 1kHz, and 1mA		
2. Insulation Resistance	100MΩ Ν	Min.	Measured	Measured at 100V DC		
3. Withstanding Voltage	No flashe	over or dielectric breakdown	150V AC for 1 minute			
4. Mating Durability	Signal C	ontact 100mΩ Max.	10 Mating Cycles			
5. Vibration	No electi	rical discontinuity of $1\mu$ s or more.	Frequency : 10 to 55Hz ; half amplitude of 0.75mm,10 cycles in each of 3 axis directions for 5 minutes/cycle, 30 cycles total			
6. Shock Resistance	No electi	rical discontinuity of $1\mu$ s or more.	Acceleration : 450m/s <sup>2</sup> , duration : 11ms, 3-axis half sine wave in both directions, 3 cycles for each			
7. Humidity	-	ontact : 100m $\Omega$ Max. n Resistance : 50m $\Omega$	Left for 96 hours at a temperature of 40 $\pm 2^\circ C$ and a humidity range from 90 to 95%			
8. Temperature Cycle	0	ontact : 100m $\Omega$ Max. n Resistance : 100m $\Omega$ Min.	-55±3°C : 30 minutes → 85±2°C : 30 minutes, 5 cycles			
9. Solder Heat Resistance		lution or melting of the resin that t performance.	t Reflow : with recommended temperature profile Hand soldering at soldering iron temperature of 350°C for 3 seconds max.			

Note 1 : Includes temperature rise caused by current flow.

1.3 Max.

1.4 Max.

1.6 Max.

Note 2 : Storage refers to long-term-storage of unused items before they are mounted on the PCB.

Operating temperature and humidity range apply when the product is not powered after PCB mounting and when temporarily stored during transportation.

0-3GHz

3-6GHz

6-12GHz

Note 3 : Use without condensation.

10. V.S.W.R.

### Materials/ Finish

Product	Part	Materials	Finish	UL Regulation
Hander / Decentaria	Insulator	LCP	Black	UL94V-0
Header / Receptacle	Contact	Phosphor Bronze	Gold Plated	_

### Product Number Structure

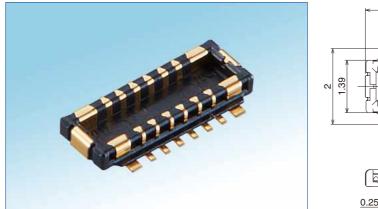
Refer to the chart below when determining the product specifications from the product number. Please select from the product numbers listed in this catalog when placing orders.

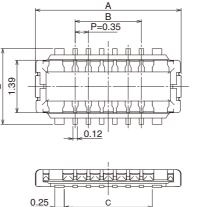
#### Header / Receptacle

<u>BM46</u> B -	*	DP	- 0.35	V	(**)
1	-	3	4	_	_

Series Name	: BM46					
2No. of Signal Contacts : 12						
Onnector Type	DP : Header DS : Receptacle					
4Contact Pitch	: 0.35mm					
<b>5</b> Termination Type	: Straight SMT					
<ul> <li>Gold plating and packaging conditions</li> <li>(51) : Gold plating Embossed tape packaging (20,000 pcs/reel)</li> <li>(53) : Gold plating</li> </ul>						
Embossed tape packaging (1,000 pcs/reel)						

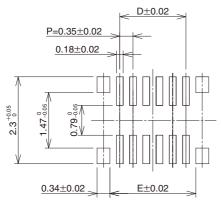
### Header



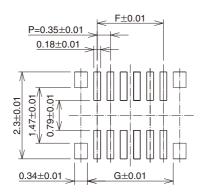




## Recommended PCB Layout



## ■Recommended Metal Mask Dimensions (Mask Thickness : 80µm)



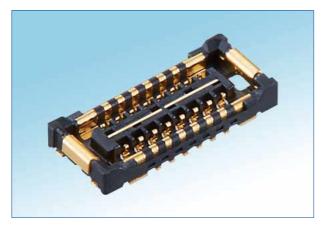
Part No.	HRS No.	No. of contacts	А	В	С	D	E	F	G
BM46B-12DP-0.35V(**)	673-7055-0 **	12	3.85	1.75	2.33	1.75	2.27	1.75	2.27

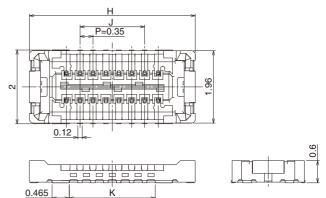
Note 1 : Please place orders in full reel quantities.

Note 2 : This connector has no polarity.

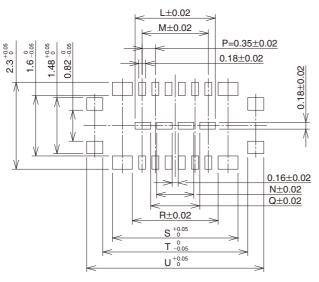


## Receptacle

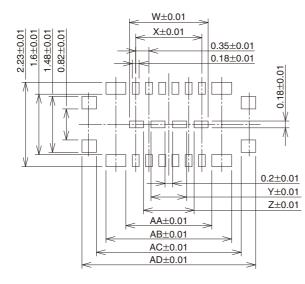




### Recommended PCB Layout



## ■Recommended Metal Mask Dimensions (Mask Thickness : 80µm)

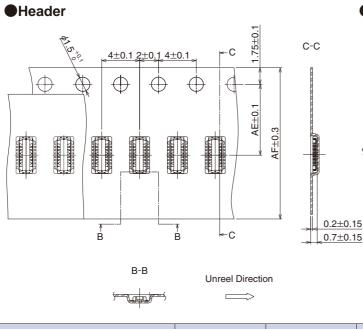


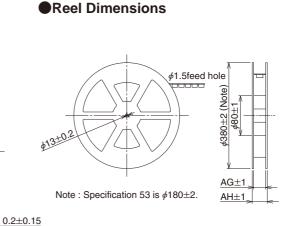
Part No.	HRS No.	No. of contacts	Н	J	К	L	М	N	Q	R	S	Т
			4.49	1.75	2.33	2.12	1.75	0.98	1.3	2.27	3.32	3.83
BM46B-12DS-0.35V(**)	673-7054-0 **	12	U	W	Х	Y	Z	AA	AB	AC	AD	
			4.68	2.08	1.75	0.94	1.34	2.27	3.32	3.83	4.59	

Note 1 : Please place orders in full reel quantities. Note 2 : This connector has no polarity.



## Embossed Tape Dimensions (IEC 60286-3, JIS C 0806)





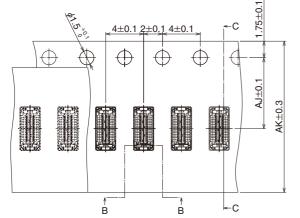
Part No.	No. of Contacts	AE	AF	AG	AH
BM46B-12DP-0.35V(**)	12	7.5	16	17.4	21.4

C-C

## Embossed Tape Dimensions (IEC 60286-3, JIS C 0806)

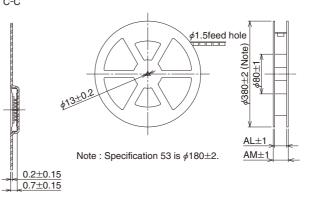
Receptacle

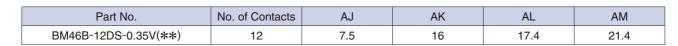




B-B Just in the second second

Unreel Direction  $\Longrightarrow$ 





### ♦ Precautions

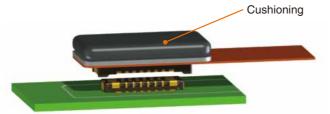
1 Decommonded Solder							
1. Recommended Solder Temperature Profile	Temperature (°C)						
remperature i rome	MIAZ200						
	250						
	220 =						
	180 <u>180°C</u>						
	150						
	150°C						
	(60 sec.) 90-120sec. MAX 60 sec.						
	(150 to 180°C) (220°C Min.)						
	[Conditions]						
	1. Peak temperature : Maximum of 250°C						
	2. Heating : 220°C min., within 60 sec						
	3. Preheating : 150 to 180°C, 90 to 120 sec						
	4. Number of Reflow Cycles : Maximum of 2 cycles						
	Note 1 - The temperature refers to the surface temperature of the DCP near the connector						
	Note 1 : The temperature refers to the surface temperature of the PCB near the connector lead.						
	Note 2 : When using nitrogen reflow, oxygen concentration must be 1000 [ppm] or more for						
	mounting. If it is less than 1000 [ppm], please contact a Hirose representative.						
	Soldering iron temperature : $340 \pm 10^{\circ}$ C :						
2. Recommended Manual Soldering Conditions	Soldering iron temperature : $340 \pm 10^{\circ}$ C ;						
0	Soldering time : within 3 seconds						
3. Recommended Stencil Thickness and Open Area	Thickness : 0.08mm						
to PCB Pattern Area Ratio	Aperture Ratio : Receptacle Side : 100%, Header Side:100%						
4. Board Warpage	A maximum of 0.02mm at the center of the connector relative to each end of the connector.						
	Cleaning is not recommended. If you clean this product, please evaluate its performance						
	before using it.						
5. Cleaning Conditions	-						
	(Cleaning may impair the mating/unmating properties and lower resistance to environmental factors)						
6. Precautions	Care should be taken when mating/unmating the connector when it is not mounted on the						
	PCB as it may cause damage/ deformation to contacts.						
	Avoid supporting the PCB only with the connectors.						
	Support it by other means such as bolts, screws, posts, etc.						
	Excessive prying during unmating/mating may result in damage.						
	In the case of hand soldering, please do not apply any flux which could cause flux wicking.						
	This product may have slight color differences due to production lot variability, but this						
	does not affect the performance.						
	Please refer to the following page for handling precautions when inserting and removing.						
	Because the product can disengage if dropped (or other impact), or by FPC routing, it is						
	advised to secure the mated connectors to the board with housings and cushioning						
	materials.						
	Do not use the connector in non-recommended conditions (i.e., rated current, rated						
	voltage, PCB design and operating environment, etc.). Such usage could lead to						
	material outgassing, ignition, or short-circuit, etc.						
	Refer to the specifications and guidelines for board pattern dimensions, board cautions,						
	and connector treatment.						
	Please contact Hirose if connector usage in conditions other than those described in the						
	specifications and the guidelines is being considered.						

#### Connector Handling Precautions

#### **Disengagement Prevention**

#### Please use cushioning

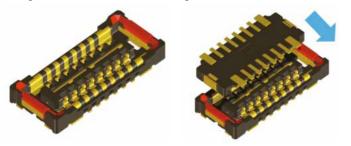
The connector may come off due to impact such as dropping. Cushioning should be large enough to cover the entire connector.



#### **Mating Method**

#### 1) Locate the guide port and align.

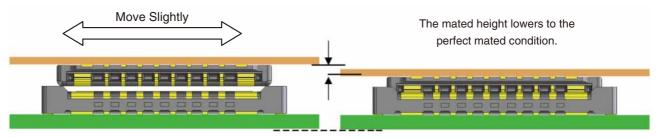
This product has a guide rib on the receptacle side to ensure proper engagement. Align the connector based on the guide rib.



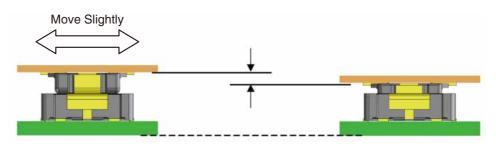
#### 2)Once aligned, the connector engages.

You can feel the mated height of the connector lower.

Move the connector forward and backward, left and right to find the guide port.



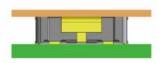
3)In the engaged state, the connectors are parallel to each other, and the connectors cannot move forward, backward, left, or right. Complete mating from this state.



#### 4) Check that mating is completed.

If one side is floating, or if it is mated diagonally, remove and re-mate.



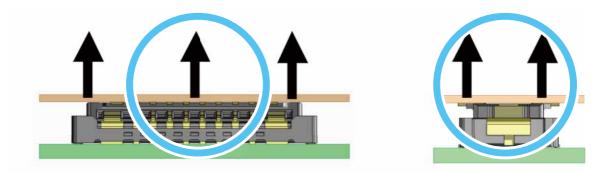




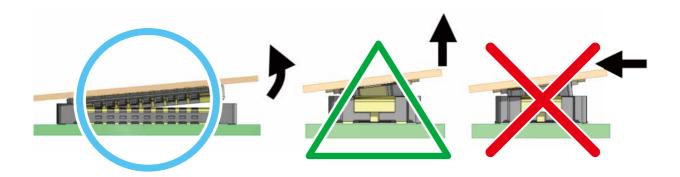
#### Handling Precautions for Connector Removal

1) When removing the connector, it is preferable to pull it out in the upward direction from the connector mounting surface.

However when removing the FPC from the circuit board it becomes more difficult to remove it vertically with higher pin counts and thin FPCs.



2) If difficult to remove, extract the connector diagonally in the direction of the pitch.
Note that removal from the widthwise side will apply a large load to the contacts. When removing from the width direction, pull the end of the FPC in the upward direction.
(When a force is applied in the horizontal direction, a large load is applied to the contact.)



3) If the FPC does not have sufficient rigidity, solder stripping or connector breakage may occur. Please use it after checking the repetitive operation with the flexible board you during a trial manufacture run. Refrain from holding the corner of the flexible board and removing it diagonally as it will result in a large load to the contacts.



The characteristics and the specifications contained herein are for reference purpose. Please refer to the latest customer drawings prior to use. The contents of this catalog are current as of date of 11/2019. Contents are subject to change without notice for the purpose of improvements.

# **Mouser Electronics**

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